

DY2S6Z000L

Silicon epitaxial planar type

For ESD protection and transient voltage suppressor

■ Features

- IEC 61000-4-2 (ESD) ±8 kV (contact) / ±15 kV (air)
- Low Clamping Voltage
- Low Capacitance
- Low Leak Current
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: AV

■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

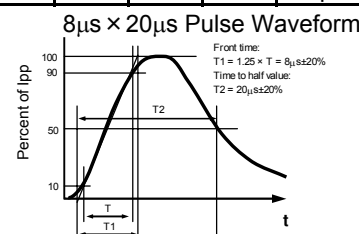
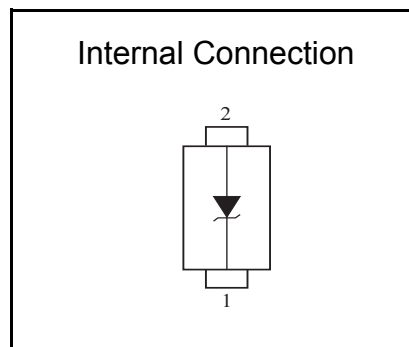
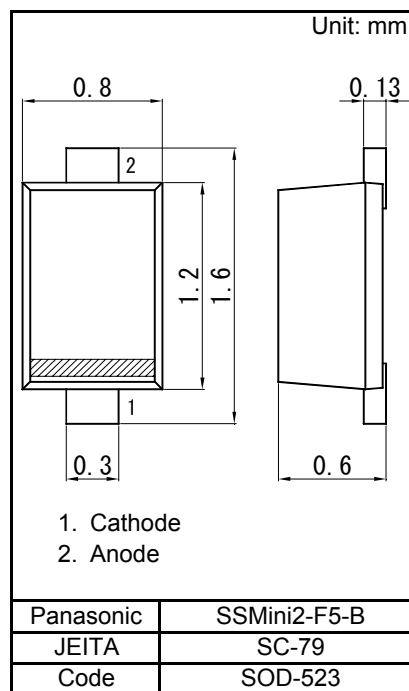
Parameter	Symbol	Rating	Unit
Total power dissipation *1	PT	150	mW
Forward current	IF	100	mA
Electrostatic discharge *2	ESD	±8	kV
Electrostatic discharge *3	ESD	±15	kV
Peak pulse power *4	Ppp	47	W
Peak pulse current *4	Ipp	2.8	A
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

- Note: *1 Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm)
 Solder in. (0.8 mm x 0.6 mm)
- *2 Test method:IEC61000_4_2
 (C = 150 pF,R = 330 Ω, contact discharge:10 times)
- *3 Test method:IEC61000_4_2 (C = 150 pF,R = 330 Ω, air discharge:10 times)
- *4 Test method:IEC61000_4_5 (tp = 8/20μs, Unrepeated)

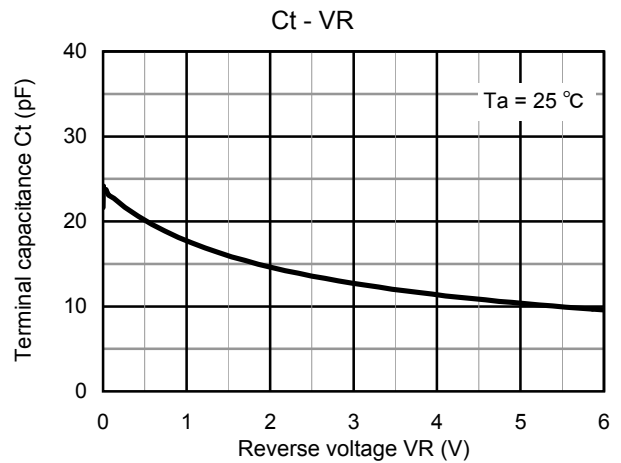
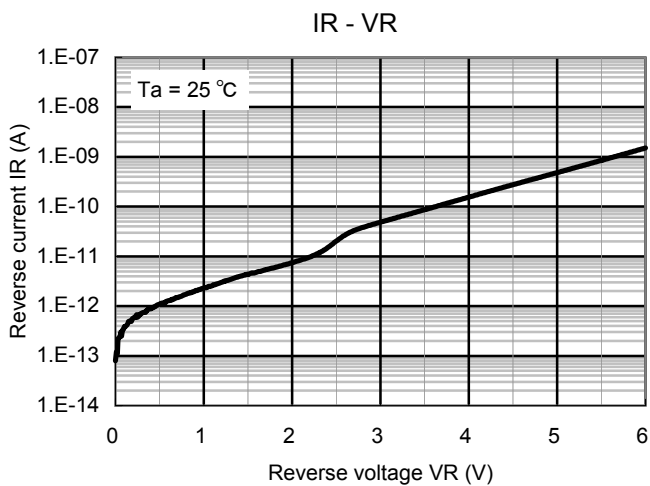
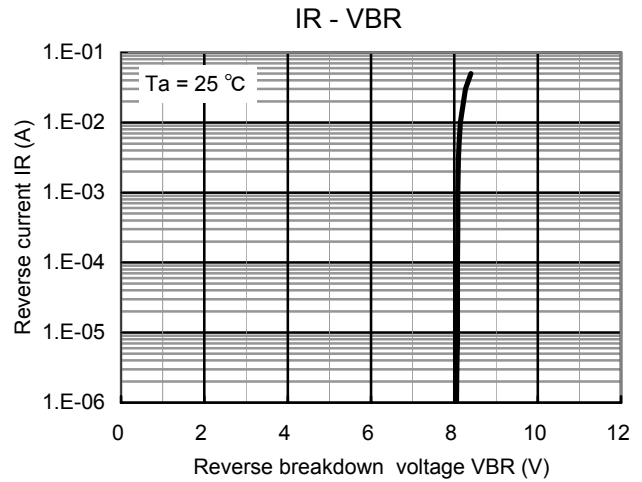
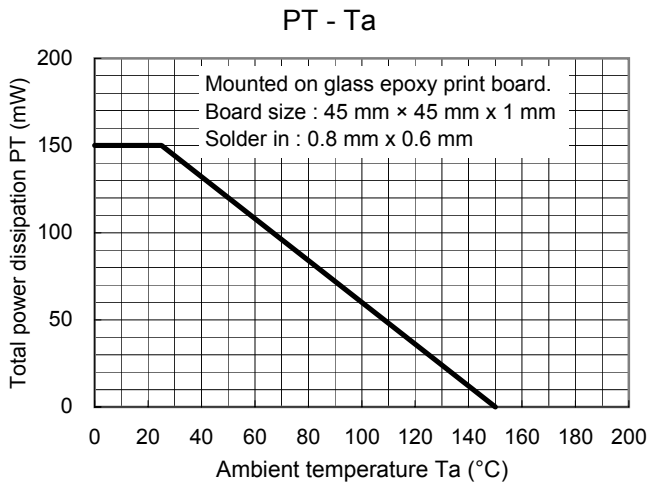
■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 10mA			1.0	V
Reverse stand-off voltage	VRWM	—			6.0	V
Reverse breakdown voltage *1, *2	VBR	IR = 5mA	7.79	8.2	8.61	V
Reverse current	IR	VR = 6V			0.05	μA
Clamping voltage *3	Vc	Ipp = 2.8A, tp = 8/20 μs			19.3	V
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		24		pF

- Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031
 Measuring methods for Diodes.
2. Absolute frequency of input and output is 5 MHz.
3. *1 The temperature must be controlled 25°C for VBR measurement.
 VBR value measured at other temperature must be adjusted to VBR (25°C)
- *2 VBR guaranteed 20 ms after current flow.
- *3 8μs × 20μs Pulse Waveform

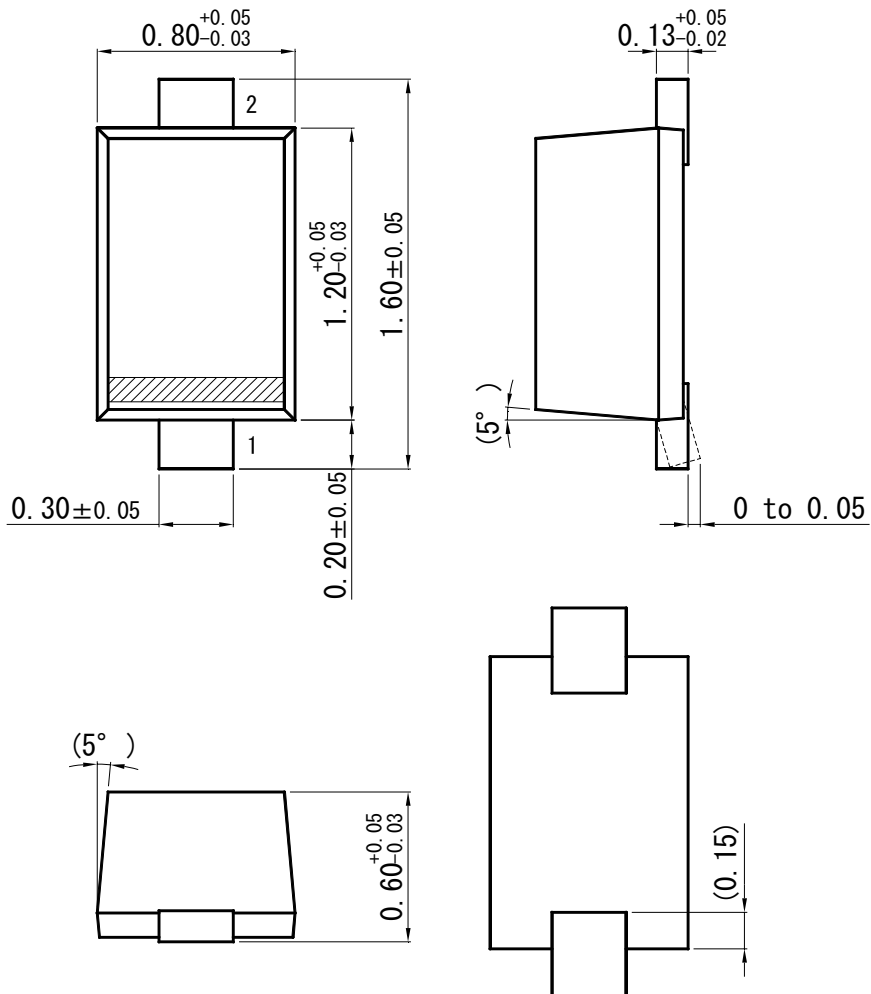


Technical Data (reference)

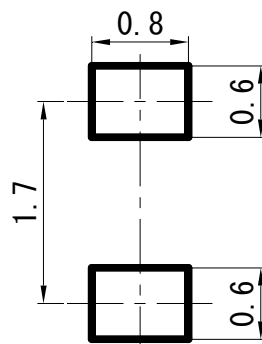


SSMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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